ABSTRACT

A lead frame material, which can be provided with an etching stop layer without requiring a troublesome process such as vapor deposition and has an excellent heat-resistance, is obtained by forming a nickel-phosphorus alloy layer (B) of 1.6 to 10 μm thickness containing 0.3 to 1.0 wt% of phosphorus on a copper or copper alloy layer (A) of 35 to 300 μm thickness, and forming an optional copper layer (C) of 0.2 to 30 μm thickness on the nickel-phosphorus alloy layer (B).